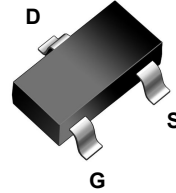
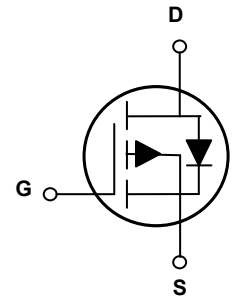


**Main Product Characteristics**

|               |              |
|---------------|--------------|
| $V_{(BR)DSS}$ | -20V         |
| $R_{DS(ON)}$  | 119mΩ (Max.) |
| $I_D$         | -2.0A        |



SOT-323



Schematic Diagram

**Features and Benefits**

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery

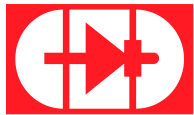


**Description**

The GSFCR2303 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

**Absolute Maximum Ratings** ( $T_A=25^{\circ}C$  unless otherwise specified)

| Parameter  | Symbol          | Max.        | Unit            |
|--|-----------------|-------------|-----------------|
| Drain-Source Voltage   | $V_{DS}$        | -20         | V               |
| Gate-to-Source Voltage   | $V_{GS}$        | $\pm 8$     | V               |
| Continuous Drain Current, @ Steady-State ( $T_A=25^{\circ}C$ ) <sup>1</sup>      | $I_D$           | -2.0        | A               |
| Continuous Drain Current, @ Steady-State ( $T_A=70^{\circ}C$ )                   |                 | -1.6        | A               |
| Pulsed Drain Current <sup>2</sup>  | $I_{DM}$        | -8          | A               |
| Power Dissipation ( $T_A=25^{\circ}C$ )  | $P_D$           | 0.45        | W               |
| Linear Derating Factor ( $T_A=25^{\circ}C$ )                                     |                 | 3.6         | mW/ $^{\circ}C$ |
| Thermal Resistance, Junction-to-Ambient (PCB Mounted, Steady-State) <sup>3</sup> | $R_{\theta JA}$ | 280         | $^{\circ}C/W$   |
| Operating Junction and Storage Temperature Range                                 | $T_J/T_{STG}$   | -55 to +150 | $^{\circ}C$     |



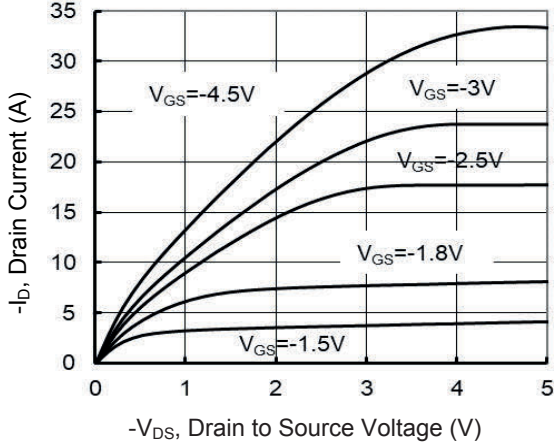
### Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise specified)

| Parameter                                       | Symbol        | Conditions   | Min. | Typ.  | Max. | Unit       |
|---|---------------|--|------|-------|------|------------|
| <b>On / Off Characteristics</b>                 |               |  |      |       |      |            |
| Drain-to-Source Breakdown Voltage               | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=-250\mu A$                                     | -20  | -     | -    | V          |
| Drain-to-Source Leakage Current                 | $I_{DSS}$     | $V_{DS}=-20V, V_{GS}=0V$                                       | -    | -     | -1   | $\mu A$    |
|   |               | $T_J=125^\circ\text{C}$  | -    | -     | -50  |            |
| Gate-to-Source Forward Leakage                  | $I_{GSS}$     | $V_{GS}=8V$  | -    | -     | 100  | nA         |
|   |               | $V_{GS}=-8V$   | -    | -     | -100 |            |
| Static Drain-to-Source On-Resistance            | $R_{DS(ON)}$  | $V_{GS}=-4.5V, I_D=-2.0A$                                      | -    | 82    | 119  | m $\Omega$ |
|   |               | $V_{GS}=-2.5V, I_D=-1.0A$                                      | -    | 100   | 119  |            |
| Gate Threshold Voltage                          | $V_{GS(th)}$  | $V_{DS}=V_{GS}, I_D=-250\mu A$                                 | -0.4 | -0.62 | -1.0 | V          |
| Forward Transconductance                        | $g_{fs}$      | $V_{DS}=5V, I_D=-2.0A$   | -    | 11    | -    | S          |
| <b>Dynamic and Switching Characteristics</b>    |               |  |      |       |      |            |
| Input Capacitance                               | $C_{iss}$     | $V_{GS}=0V, V_{DS}=-10V,$<br>$f=1\text{MHz}$                   | -    | 438   | -    | pF         |
| Output Capacitance                              | $C_{oss}$     |  | -    | 76    | -    |            |
| Reverse Transfer Capacitance                    | $C_{rss}$     |  | -    | 63    | -    |            |
| Total Gate Charge                               | $Q_g$         | $I_D=-2.0A, V_{DS}=-10V,$<br>$V_{GS}=-10V$                     | -    | 5.4   | -    | nC         |
| Gate-to-Source Charge                           | $Q_{gs}$      |  | -    | 1.2   | -    |            |
| Gate-to-Drain ("Miller") Charge                 | $Q_{gd}$      |  | -    | 1.3   | -    |            |
| Turn-on Delay Time                              | $t_{d(on)}$   | $V_{GS}=-4.5V, V_{DS}=-10V,$<br>$I_D=-1A, R_G=3.0\Omega$       | -    | 6.5   | -    | nS         |
| Rise Time                                       | $t_r$         |  | -    | 21    | -    |            |
| Turn-Off Delay Time                             | $t_{d(off)}$  |  | -    | 37    | -    |            |
| Fall Time                                       | $t_f$         |  | -    | 34    | -    |            |
| Gate Resistance                                 | $R_g$         | $f=1\text{MHz}$  | -    | 5.1   | -    | $\Omega$   |
| <b>Source-Drain Ratings and Characteristics</b> |               |  |      |       |      |            |
| Continuous Source Current (Body Diode)          | $I_S$         | MOSFET symbol showing the integral reverse p-n junction diode. | -    | -     | -2.0 | A          |
| Pulsed Source Current (Body Diode)              | $I_{SM}$      |  | -    | -     | -8   | A          |
| Diode Forward Voltage                           | $V_{SD}$      | $I_S=-1.0A, V_{GS}=0V$   | -    | -0.9  | -1.2 | V          |

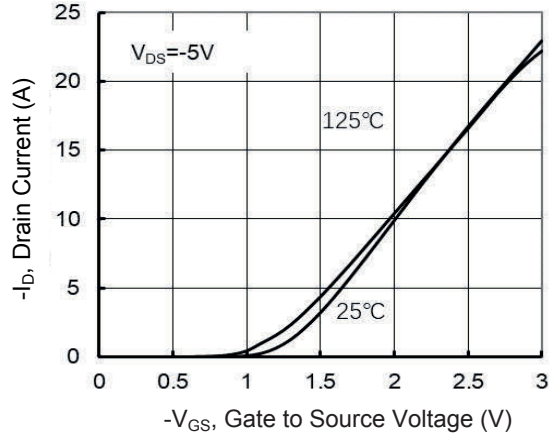
## Notes:

1. Pulse test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
2. Repetitive rating; pulse width limited by max. junction temperature.
3. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

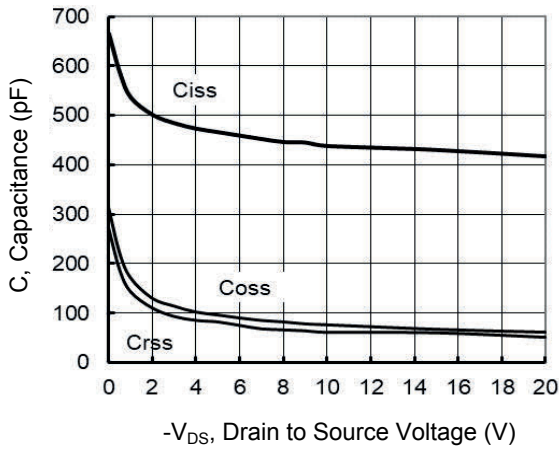
**Typical Electrical and Thermal Characteristic Curves**



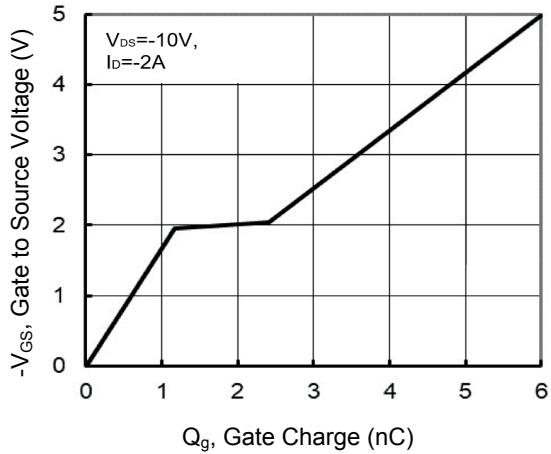
**Figure 1. Typical Output Characteristics**



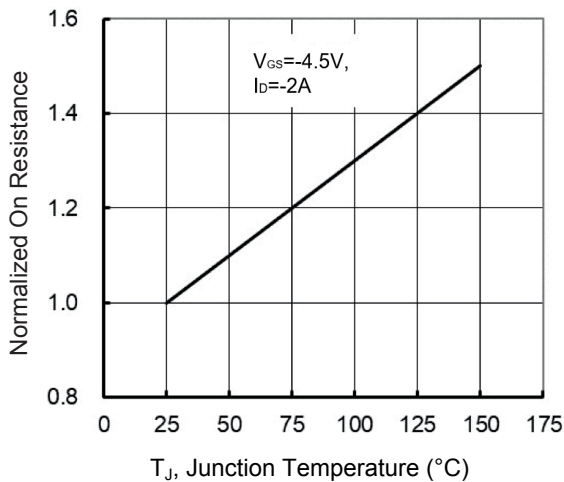
**Figure 2. Typical Transfer Characteristics**



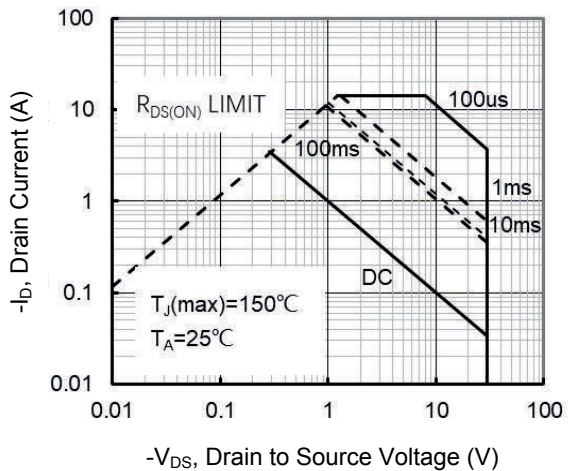
**Figure 3. Capacitance vs. Drain to Source Voltage**



**Figure 4. Gate Charge**

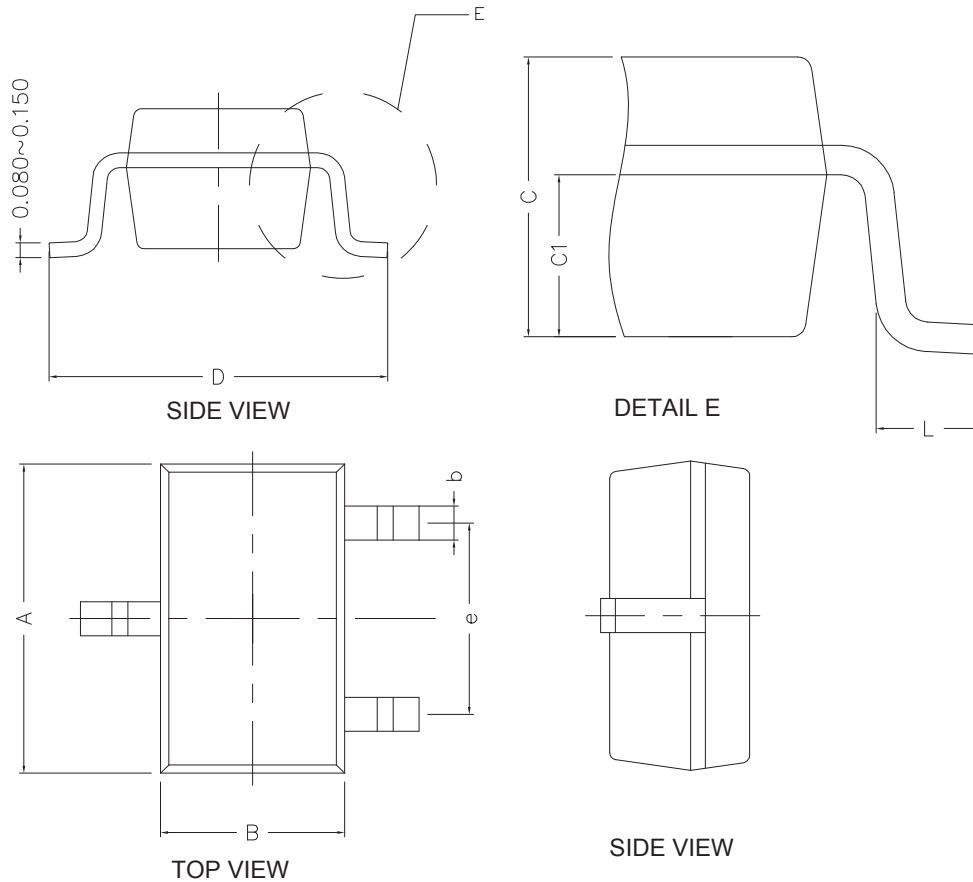


**Figure 5. Normalized  $R_{DS(ON)}$  vs.  $T_J$**



**Figure 6. Safe Operation Area**

**Package Outline Dimensions (SOT-323)**



| Symbol | Dimensions In Millimeters |      | Dimensions In Inches |       |
|--------|---------------------------|------|----------------------|-------|
|        | Min.                      | Max. | Min.                 | Max.  |
| A      | 2.00                      | 2.20 | 0.079                | 0.087 |
| B      | 1.15                      | 1.35 | 0.045                | 0.053 |
| C      | 0.90                      | 1.00 | 0.035                | 0.039 |
| C1     | 0.50                      | 0.60 | 0.020                | 0.024 |
| D      | 2.10                      | 2.50 | 0.083                | 0.098 |
| L      | 0.22                      | 0.50 | 0.009                | 0.020 |
| b      | 0.20                      | 0.40 | 0.008                | 0.016 |
| e      | 1.30 TYP                  |      | 0.051 TYP            |       |

**Order Information**

| Device    | Package | Marking | Packaging   | SPQ             |
|-----------|---------|---------|-------------|-----------------|
| GSFCR2303 | SOT-323 | W2303   | Tape & Reel | 3,000pcs / Reel |

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)